Microchip Technology - DSPIC33FJ32MC101T-I/SO Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

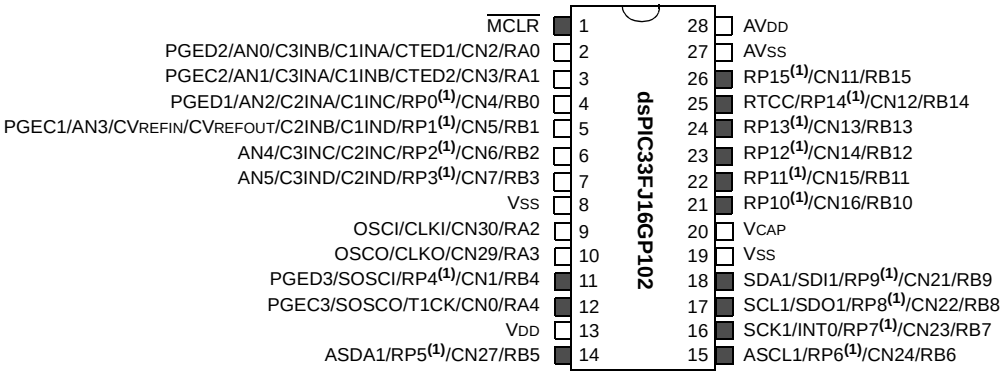
Applications of "Embedded - Microcontrollers"

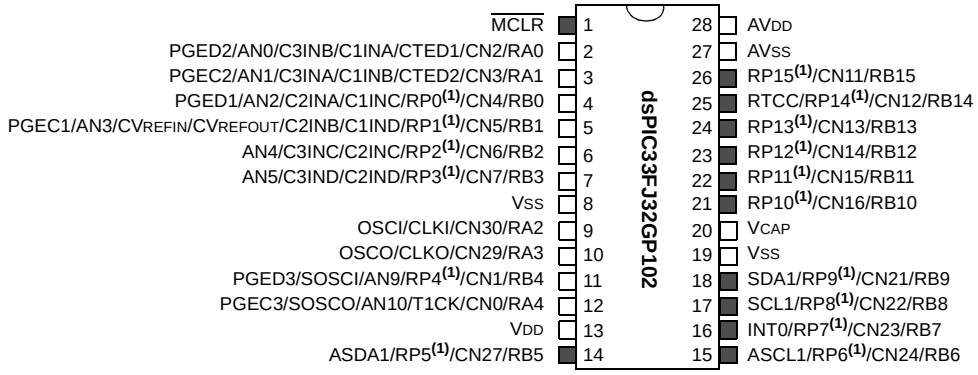
Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	15
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc101t-i-so

Pin Diagrams (Continued)

28-Pin SPDIP/SOIC/SSOP

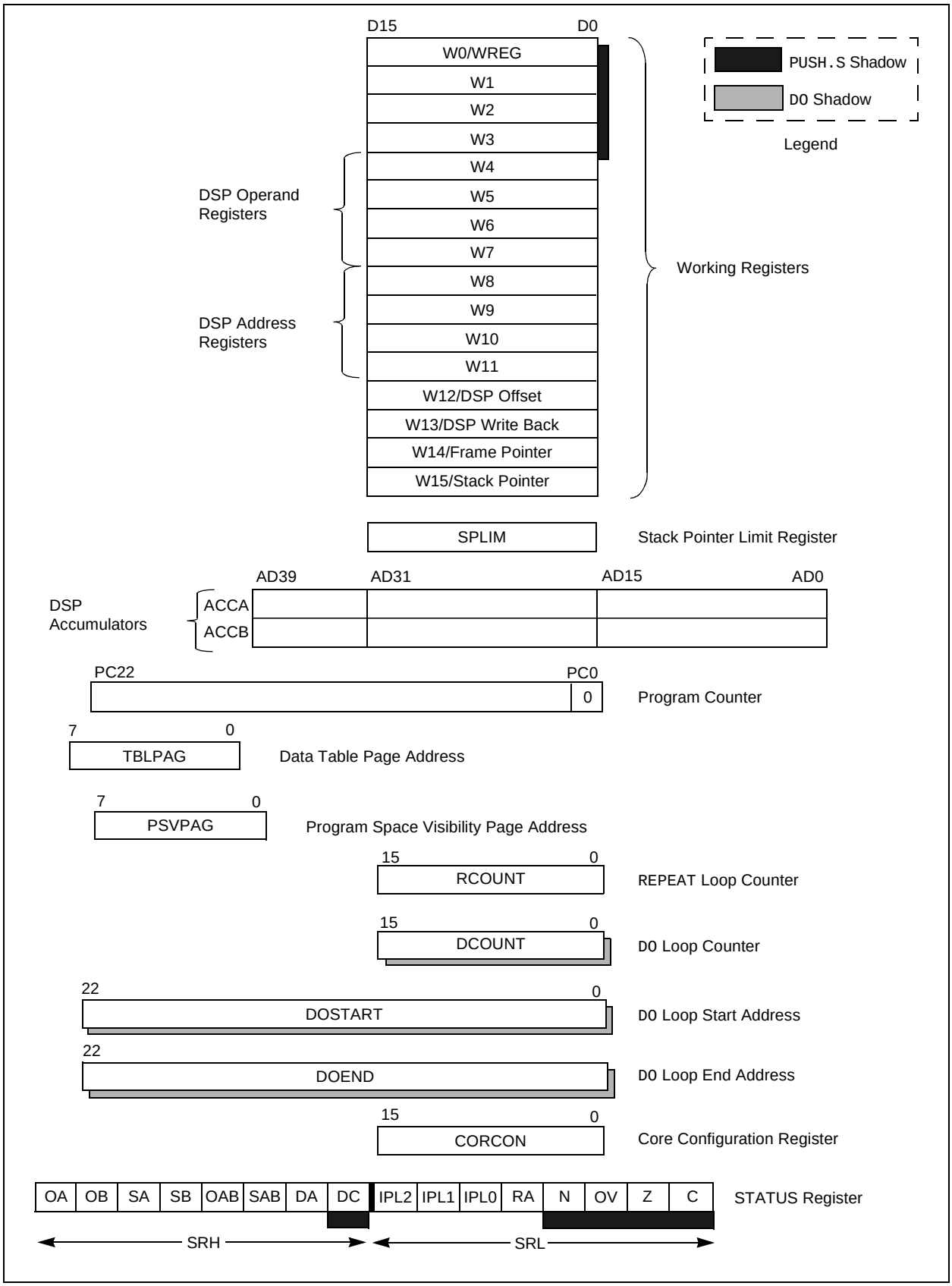
■ = Pins are up to 5V tolerant





Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

FIGURE 3-2: dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104 PROGRAMMER'S MODEL



NOTES:

4.6 Interfacing Program and Data Memory Spaces

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 architecture uses a 24-bit-wide program space and a 16-bit-wide data space. The architecture is also a modified Harvard scheme, meaning that data can also be present in the program space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 architecture provides two methods by which program space can be accessed during operation:

- Using table instructions to access individual bytes, or words, anywhere in the program space
- Remapping a portion of the program space into the data space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for lookups from a large table of static data. The application can only access the lsw of the program word.

4.6.1 ADDRESSING PROGRAM SPACE

Since the address ranges for the data and program spaces are 16 and 24 bits, respectively, a method is needed to create a 23-bit or 24-bit program address from 16-bit data registers. The solution depends on the interface method to be used.

For table operations, the 8-bit Table Page (TBLPAG) register is used to define a 32K word region within the program space. This is concatenated with a 16-bit EA to arrive at a full 24-bit program space address. In this format, the MSb of TBLPAG is used to determine if the operation occurs in the user memory (TBLPAG<7> = 0) or the configuration memory (TBLPAG<7> = 1).

For remapping operations, the 8-bit Program Space Visibility (PSVPAG) register is used to define a 16K word page in the program space. When the MSb of the EA is '1', PSVPAG is concatenated with the lower 15 bits of the EA to form a 23-bit program space address. Unlike table operations, this limits remapping operations strictly to the user memory area.

Table 4-42 and Figure 4-9 show how the program EA is created for table operations and remapping accesses from the data EA.

TABLE 4-42: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>		Data EA<14:0>(1)	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

REGISTER 7-17: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U1RXIP2	U1RXIP1	U1RXIP0	—	SPI1IP2	SPI1IP1	SPI1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI1EIP2	SPI1EIP1	SPI1EIP0	—	T3IP2	T3IP1	T3IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPI1EIP<2:0>:** SPI1 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **T3IP<2:0>:** Timer3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 10-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T3CKR4	T3CKR3	T3CKR2	T3CKR1	T3CKR0
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T2CKR4	T2CKR3	T2CKR2	T2CKR1	T2CKR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **T3CKR<4:0>:** Assign Timer3 External Clock (T3CK) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **T2CKR<4:0>:** Assign Timer2 External Clock (T2CK) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 10-7: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	OCFAR4	OCFAR3	OCFAR2	OCFAR1	OCFAR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **OCFAR<4:0>:** Assign Output Capture A (OCFA) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 12-2: T3CON: TIMER3 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(2)	—	TSIDL(1)	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE(2)	TCKPS1(2)	TCKPS0(2)	—	—	TCS(2)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timer3 On bit(2)
1 = Starts 16-bit Timer3
0 = Stops 16-bit Timer3

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timer3 Stop in Idle Mode bit(1)
1 = Discontinues timer operation when device enters Idle mode
0 = Continues timer operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timer3 Gated Time Accumulation Enable bit(2)
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timer3 Input Clock Prescale Select bits(2)
11 = 1:256 prescale value
10 = 1:64 prescale value
01 = 1:8 prescale value
00 = 1:1 prescale value

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timer3 Clock Source Select bit(2)
1 = External clock from T3CK pin
0 = Internal clock (FOSC/2)

bit 0 **Unimplemented:** Read as '0'

Note 1: When 32-bit timer operation is enabled (T32 = 1) in the Timer2 Control register (T2CON<3>), the TSIDL bit must be cleared to operate the 32-bit timer in Idle mode.

2: When the 32-bit timer operation is enabled (T32 = 1) in the Timer2 Control register (T2CON<3>), these bits have no effect.

REGISTER 15-4: PxSECMP: PWMx SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTDIR(1)	SEVTCMP<14:8>(2)						
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0>(2)							
bit 7							bit 0

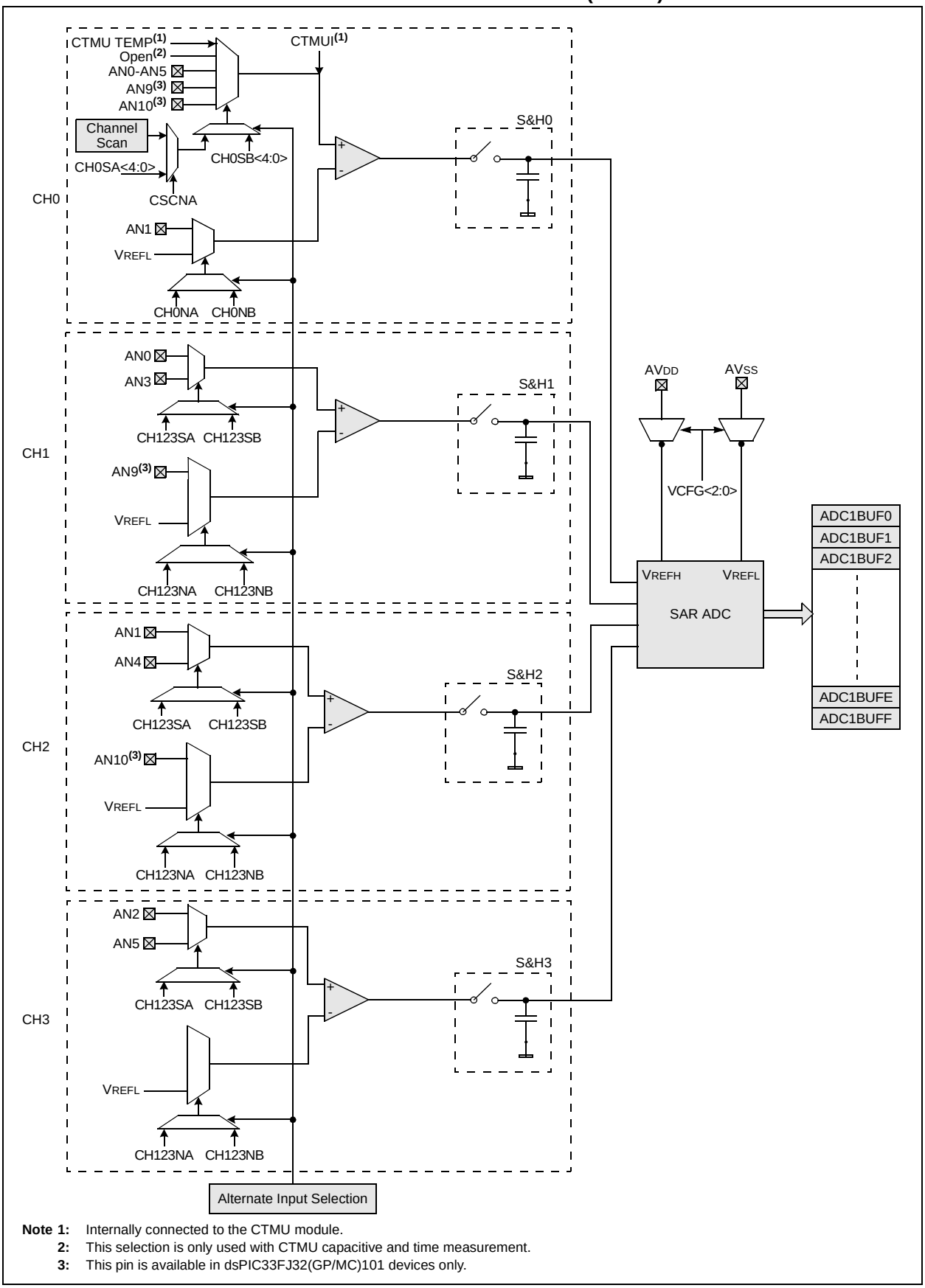
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SEVTDIR:** Special Event Trigger Time Base Direction bit(1)
1 = A Special Event Trigger will occur when the PWMx time base is counting down
0 = A Special Event Trigger will occur when the PWMx time base is counting up

bit 14-0 **SEVTCMP<14:0>:** Special Event Compare Value bits(2)

Note 1: SEVTDIR is compared with PTDIR (PxTMR<15>) to generate the Special Event Trigger.
2: PxSECMP<14:0> is compared with PxTMR<14:0> to generate the Special Event Trigger.

FIGURE 19-2: ADC1 BLOCK DIAGRAM FOR dsPIC33FJXX(GP/MC)102 DEVICES



Note 1: Internally connected to the CTMU module.
2: This selection is only used with CTMU capacitive and time measurement.
3: This pin is available in dsPIC33FJ32(GP/MC)101 devices only.

REGISTER 20-2: CMxCON: COMPARATOR x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator x Enable bit
1 = Comparator x is enabled
0 = Comparator x is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator x output is inverted
0 = Comparator x output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator x event according to EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator x event did not occur

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$
When CPOL = 1 (inverted polarity):
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt is generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.
01 = Trigger/event/interrupt is generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.
00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

21.2 RTCC Control Registers

REGISTER 21-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1)

R/W-0	U-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0
RTCEN(2)	—	RTCWREN	RTCSYNC	HALFSEC(3)	RTCOE	RTCPTR1	RTCPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **RTCEN:** RTCC Enable bit(2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **RTCWREN:** RTCC Value Registers Write Enable bit
1 = RTCVALH and RTCVALL registers can be written to by the user
0 = RTCVALH and RTCVALL registers are locked out from being written to by the user

bit 12 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTCVALH, RTCVALL and ALCFGRPT registers can change while reading, due to a rollover ripple, resulting in an invalid data read. If the register is read twice and the results are the same data, the data can be assumed to be valid.
0 = RTCVALH, RTCVALL or ALCFGRPT registers can be read without concern over a rollover ripple

bit 11 **HALFSEC:** Half-Second Status bit(3)
1 = Second half period of a second
0 = First half period of a second

bit 10 **RTCOE:** RTCC Output Enable bit
1 = RTCC output is enabled
0 = RTCC output is disabled

bit 9-8 **RTCPTR<1:0>:** RTCC Value Register Window Pointer bits
Points to the corresponding RTCC Value registers when reading RTCVALH and RTCVALL registers; the RTCPTR<1:0> value decrements on every read or write of RTCVALH until it reaches '00'.
RTCVAL<15:8>:
00 = MINUTES
01 = WEEKDAY
10 = MONTH
11 = Reserved
RTCVAL<7:0>:
00 = SECONDS
01 = HOURS
10 = DAY
11 = YEAR

Note 1: The RCFGCAL register is only affected by a POR.
2: A write to the RTCEN bit is only allowed when RTCWREN = 1.
3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

23.0 SPECIAL FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Programming and Diagnostics"** (DS70207) and **"Device Configuration"** (DS70194) in the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

23.1 Configuration Bits

The Configuration Shadow register bits can be configured (read as '0') or left unprogrammed (read as '1') to select various device configurations. These read-only bits are mapped starting at program memory location, 0xF80000. A detailed explanation of the various bit functions is provided in Table 23-4.

Note that address, 0xF80000, is beyond the user program memory space and belongs to the configuration memory space (0x800000-0xFFFFFF), which can only be accessed using Table Reads.

In dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the two words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 23-2. These are packed representations of the actual device Configuration bits, whose actual locations are distributed among several locations in configuration space. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Word for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The upper byte of all Flash Configuration Words in program memory should always be '1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration Words, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

25.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

25.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

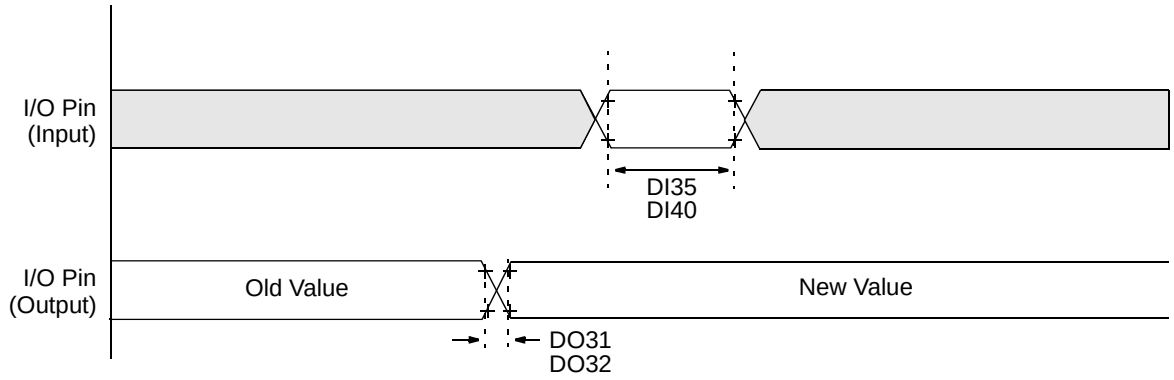
Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

FIGURE 26-3: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

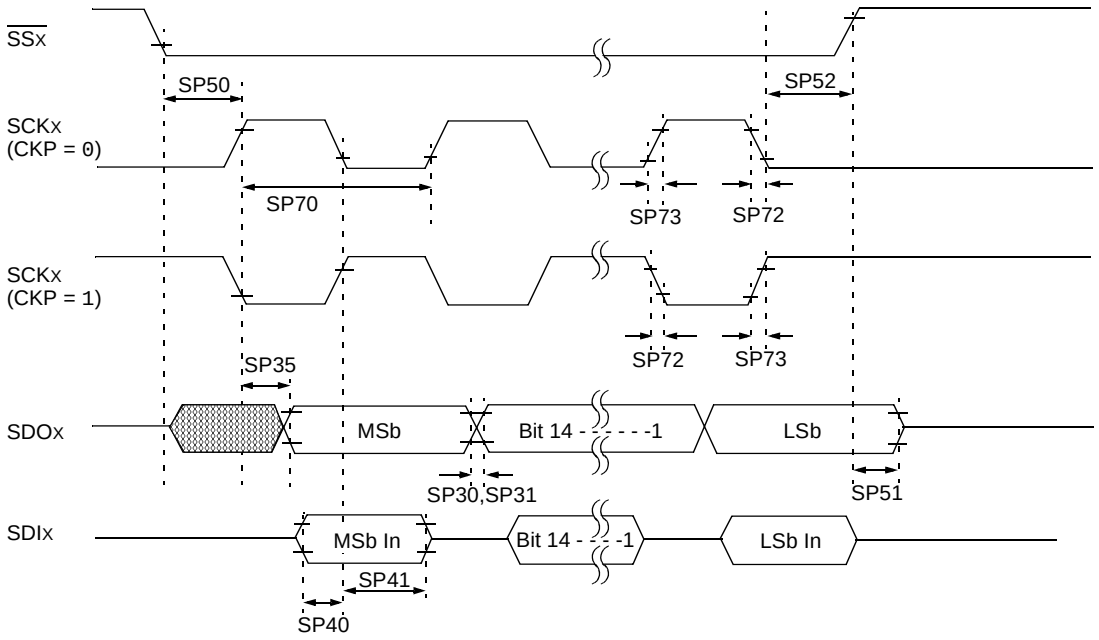
TABLE 26-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx Pin High or Low Time (input)	25	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

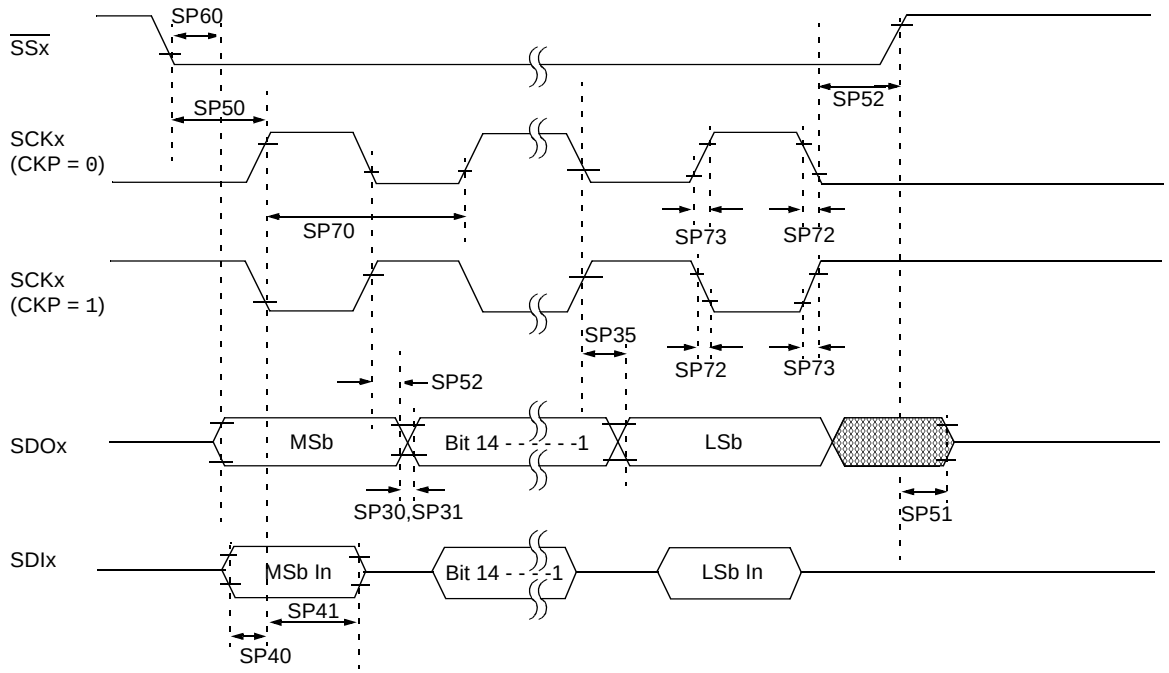
2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 26-18: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



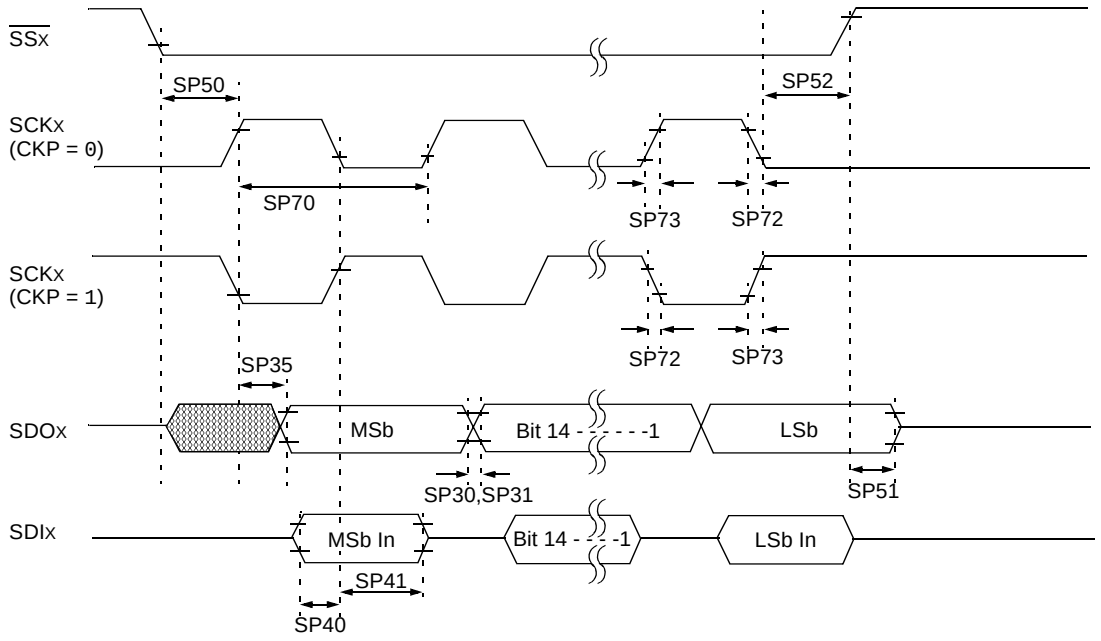
Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-24: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-26: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-50: COMPARATOR TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
300	TRESP	Response Time(1,2)	—	150	400	ns	
301	TMC2OV	Comparator Mode Change to Output Valid(1)	—	—	10	µs	
302	TON2OV	Comparator Enabled to Output Valid(1)	—	—	10	µs	

Note 1: Parameters are characterized but not tested.

2: Response time is measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

TABLE 26-51: COMPARATOR MODULE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
D300	VIOFF	Input Offset Voltage(1)	-20	±10	20	mV	
D301	VICM	Input Common-Mode Voltage(1)	0	—	AVDD – 1.5V	V	
D302	CMRR	Common-Mode Rejection Ratio(1)	-54	—	—	dB	
D305	IVREF	Internal Voltage Reference(1)	1.116	1.24	1.364	V	

Note 1: Parameters are characterized but not tested.

TABLE 26-52: COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

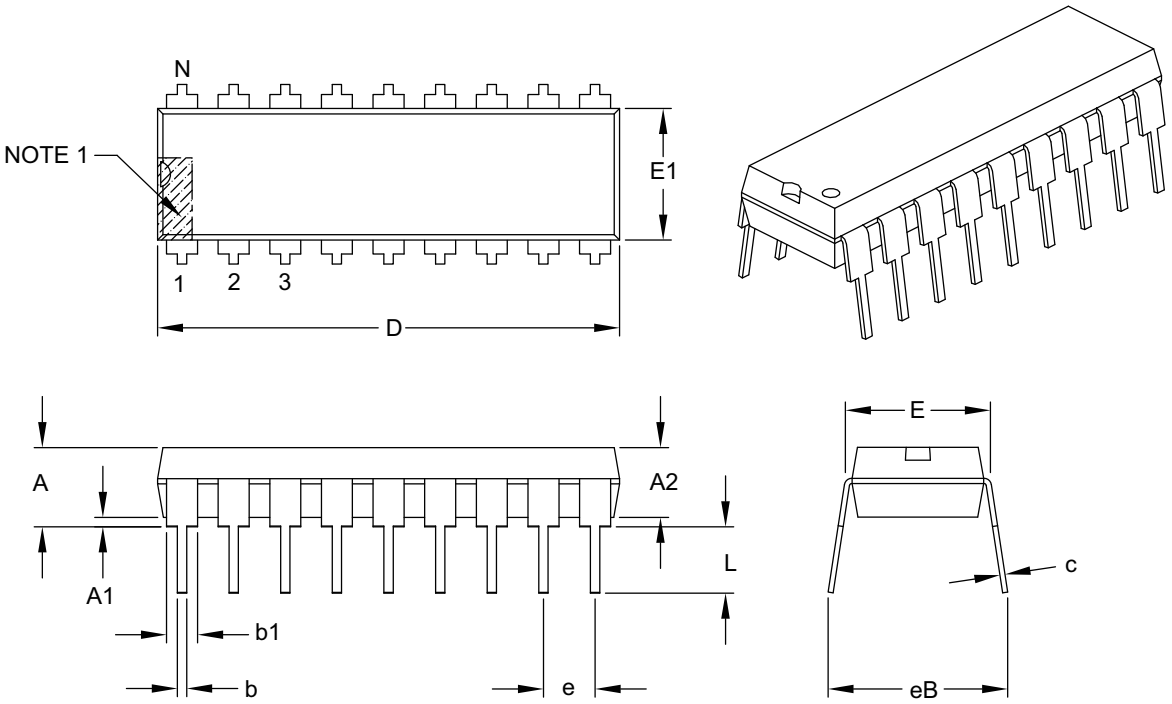
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
VR310	TSET	Settling Time(1)	—	—	10	µs	

Note 1: Settling time measured while CVRR = 1 and the CVR<3:0> bits transition from '0000' to '1111'.

28.2 Package Details

18-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.880	.900	.920
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.014
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-007B